

AP7375Q AUTOMOTIVE COMPLIANT WIDE INPUT VOLTAGE RANGE

300mA ULDO REGULATOR

Description

The AP7375Q series is a wide input voltage range (45V), low quiescent current (2.1uA), low-dropout linear regulator (LDO) able to provide 300mA load current. The AP7375Q family of LDOs offers an EN pin to enable and disable the LDO output. The EN pin can take an input voltage of 45V.

The device provides a very fast response against line voltage transient and load current transient, and ensures no overshoot voltage occurs during start up and short-circuit recovery. It also features integrated short-circuit and thermal-shutdown protection.

The AP7375Q has 1.8V, 3.0V, 3.3V, and 5.0V fixed output voltage versions, and is available in the SOT89, SO-8EP, SOT25, SOT25R and U-DFN2020-6 (SWP) (Type UXC) packages.

Features

- Wide Input Voltage Range: 3V to 45V
- Maximum Output Current: 300mA
- Low Dropout Voltage: $V_{DROP} = 35mV@I_{OUT} = 10mA$ (Typ.) V_{DROP} = 350mV@ I_{OUT} = 100mA (Typ.)
- Low Quiescent Current: 2.1µA (Typ.)
- Fixed Output Voltages: 1.8V, 3.0V, 3.3V and 5.0V
- High Output Voltage Accuracy: ±2%
- High PSRR: 85dB@1kHz
- Excellent Line/Load Regulation
- **Thermal Shutdown Function**
- Short-Current Protection Function
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The AP7375Q is suitable for automotive applications requiring specific change control; this part is AEC-Q100 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/guality/product-definitions/

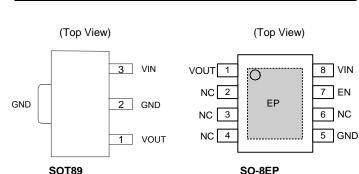
Applications

- Powering MCUs and CAN/LIN transceivers
- Automotive head units
- EV and HEV battery management systems
- Body control modules
- Transmission control units (TCUs)

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



SOT89

V_{IN} 1

GND 2

EN 3

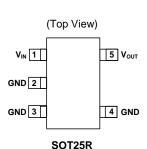
(Top View)

SOT25

5 Vout

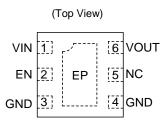
4 NC

Pin Assignments



ΕN

7

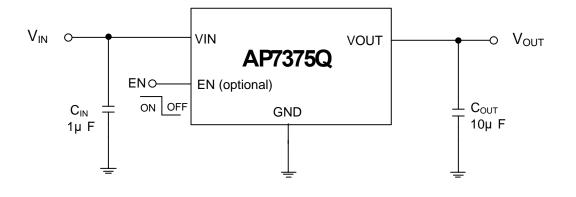


U-DFN2020-6 (SWP) (Type UXC)

Future Product



Typical Applications Circuit



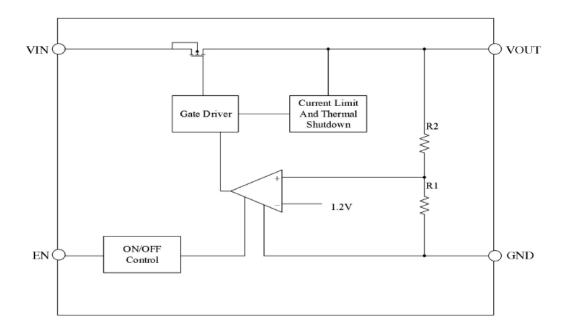
Pin Descriptions

	Pin Number						
SOT89	SO-8EP	SOT25	SOT25R	U-DFN2020-6 (SWP) (Type UXC)	Pin Name	Function	
3	8	1	1	1	VIN	Input voltage	
2	5	2	2, 3, 4	3, 4	GND	Ground	
-	7	3	-	2	EN	Enable	
1	1	5	5	6	VOUT	Regulated output voltage	
-	2, 3, 4, 6	4	-	5	NC	Not Connected internally, recommend connect to GND to maximize PCB copper for thermal dissipation.	
-	EP	-	-	-	Expose Pad	In PCB layout, prefer to use large copper area to cover this pad for better thermal dissipation, then connect this area to GND or leave it open. However, do not use it as GND electrode function alone	



AP7375Q

Functional Block Diagram



Absolute Maximum Ratings

Symbol	Parameter	Rating		Unit
V _{IN}	Supply Input Voltage	-0.3 ~ 55		V
Vout	Regulated Output Voltage	-0.3 ~ 6		V
V _{EN}	EN to GND	-0.3 ~ 55		V
Іоит	Output Current	Internally limited		mA
T _{LEAD}	Lead Temperature (Soldering, 10sec)	+260		٥C
TJ	Operating Junction Temperature	+150		°C
T _A	Operating Ambient Temperature	-40 to +125		°C
		SOT89	94.5	
<u> </u>	Thermal Resistance	SO-8EP	47.7	
θ _{JA}	(Junction to Ambient)	SOT25	135.5	°C/W
		U-DFN2020-6 (SWP) (Type UXC)	TBD	
T _{STG}	Storage Temperature Range	-40 to +150		°C
CDM	ESD (Charge Device Model)	±1.5		kV
HBM	ESD (Human Body Model)	3		kV

4. a). Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended period may affect device reliability.

b). Ratings apply to ambient temperature at +25°C. The JEDEC STD.51 High-K board design used to derive this data was a 3 inch x 3 inch multilayer board with 1oz. internal power and ground planes and 2oz. copper traces on the top and bottom of the board.

Note:



Recommended Operating Conditions

Symbol	Parameter	Min	Тур	Мах	Unit
Vin	Supply Input Voltage	3.0	_	45	V
Vout	Output Voltage	_	_	5	V
TJ	Operating Junction Temperature	-40	_	+125	°C
C _{IN}	Input Capacitor	_	1	_	μF
Соит	Output Capacitor	1	10	_	μF

Electrical Characteristics (T_A = -40°C~ 125°C, I_{OUT} = 1mA, C_{IN}=1µF, C_{OUT} =10µF ceramic capacitor, V_{IN} = V_{OUTNOM} +2.0V)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _{IN}	Input Voltage	_	3	_	45	V
I _{GND}	Quiescent Current	VIN = 12V, No load	—	2.1	8	μA
Vout	Output Voltage	VIN = 12V, IOUT = 10 mA	V _{OUT} x98%	_	V _{OUT} x102%	V
IOUT_MAX	Output Current	_	300	350	—	mA
		$I_{OUT} = 10mA$, $V_{IN} = V_{OUTNOM} - 0.1V$	—	35	80	mV
V _{DROP}	Dropout Voltage (Note 5)	$I_{OUT} = 100 \text{mA}, V_{IN} = V_{OUTNOM} - 0.1 \text{V}$	—	350	580	mV
		$I_{OUT} = 300 \text{mA}, V_{IN} = V_{OUTNOM} - 0.1 \text{V}, T_A = 25^{\circ}$		1200	1400	mV
ΔV _{OUT} (ΔI _{OUT})	Load Regulation (Note 6)	$V_{IN} = 12V, 1mA \le I_{OUT} \le 100mA$	—	0.02	0.025	%/mA
ΔV _{OUT} (ΔV _{IN})	Line Regulation	V_{OUTNOM} + 2V \leq V _{IN} \leq 45 V, Iout = 1 mA	_	0.01	0.02	%/V
ILIMIT	Current Limit	_	_	500	—	mA
T _{OTSD}	Thermal Shutdown Temperature	_	_	+150	—	°C
T _{HYOTSD}	Thermal Shutdown Hysteresis	_	_	+10	_	°C
PSRR	Power Supply Rejection Ratio	$V_{IN} = 12V, I_{OUT} = 10mA,$ $V_{OUT} = 3.3V@1kHz$	_	85	_	dB
Vn	Output Noise Voltage	BW = 10Hz to 100kHz, I_{OUT} = 30mA	_	120	_	µVrms
VENH	EN High Level	Enabled	1	_	—	V
VENL	EN Low Level	Disabled	_	_	0.4	V
		SOT89	—	43.7	_	
0	Thermal Resistance Junction to	SO-8EP	—	17.4	—	°C/W
θις	Case (Note 4)	SOT25	_	36.7	_	C/vv
		U-DFN2020-6 (SWP) (Type UXC)		TBD	_	

4. a). Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended period may affect device reliability. Note:

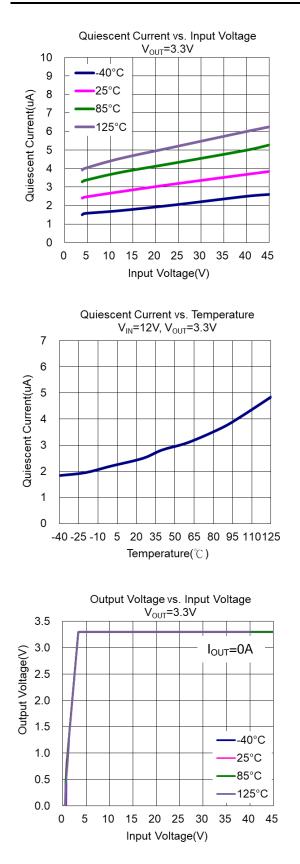
b). Ratings apply to ambient temperature at +25°C. The JEDEC STD.51 High-K board design used to derive this data was a 3 inch x 3 inch multilayer board with 1oz. internal power and ground planes and 2oz. copper traces on the top and bottom of the board.

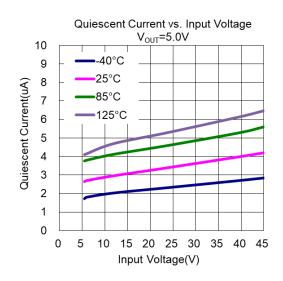
5. Dropout voltage is the voltage difference between the input and output at which the output voltage drops 100mV below its nominal value. This

parameter only applies to output voltages above 3.0V since minimum VIN = 3.0V. 6. The AP7375Q internal circuitry is not fully operational until V_{IN} is at least the greater of 3V or ($V_{OUT}+V_{DROPOUT(MAX)}$).

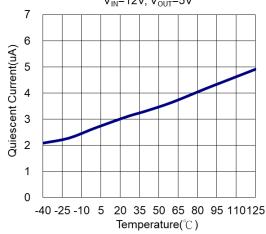


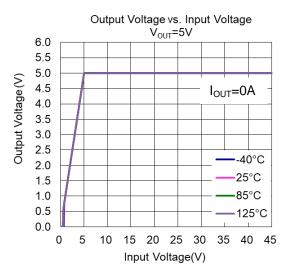
Performance Characteristics





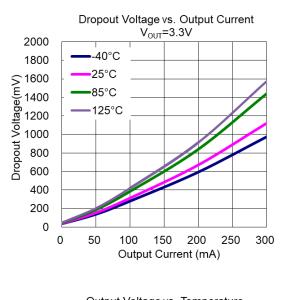
Quiescent Current vs. Temperature V_{IN} =12V, V_{OUT} =5V

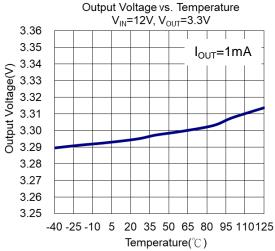


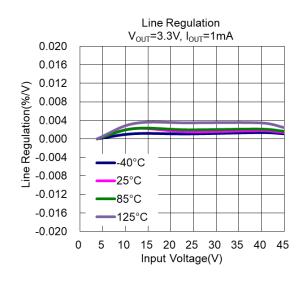


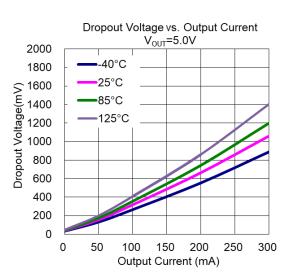


Typical Characteristics

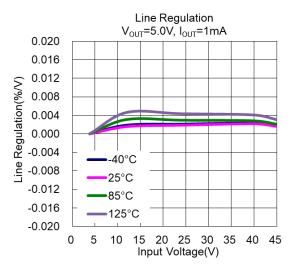






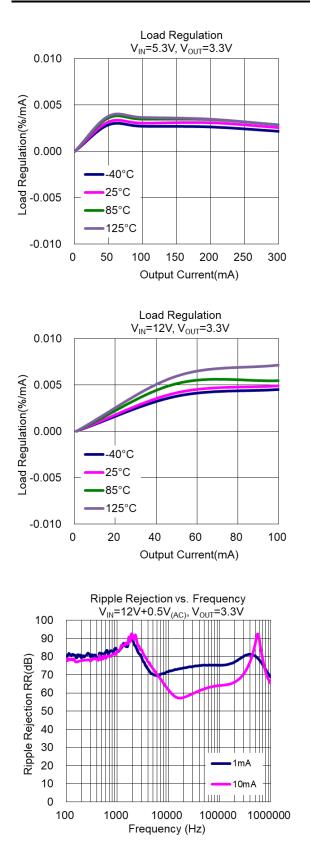


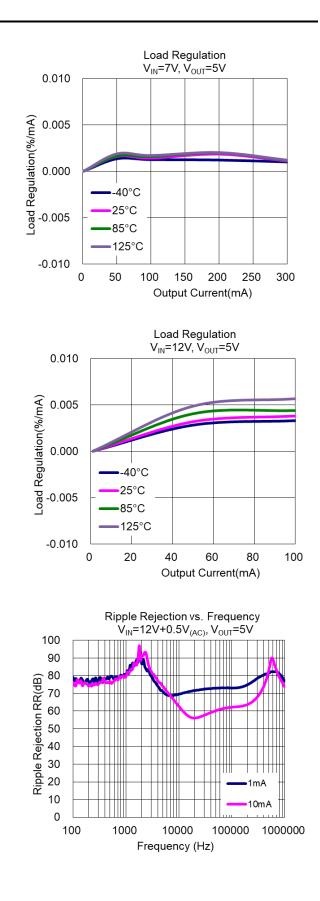
Output Voltage vs. Temperature VIN=12V, V_{OUT}=5V 5.14 5.12 5.10 5.08 5.06 5.04 5.04 5.02 5.04 5.00 5.04 5.02 5.04 5.00 5.00 4.98 4.96 4.94 4.92 4.90 4.88 -40 -25 -10 5 20 35 50 65 80 95 110125 Temperature(°C)





Typical Characteristics (continued)

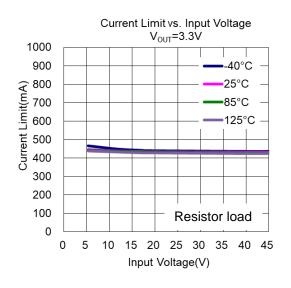


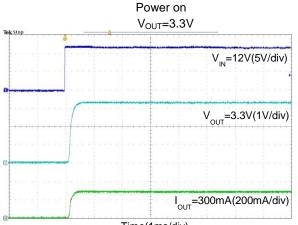




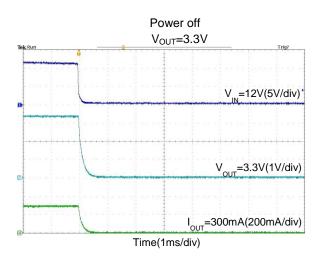
AP7375Q

Typical Characteristics (continued)

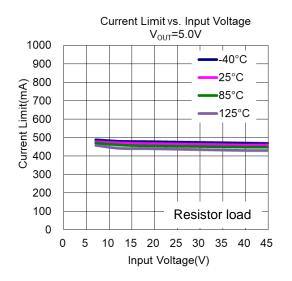


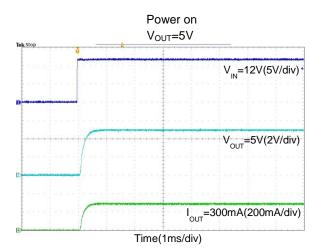


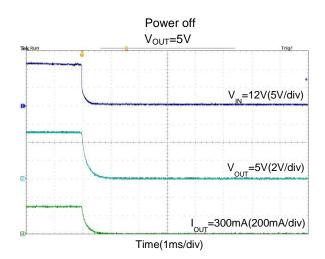
Time(1ms/div)



Line Transient Response V_{OUT} =3.3V



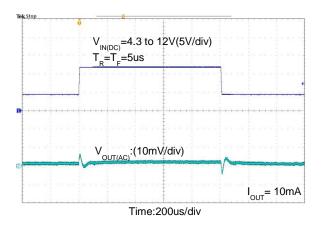


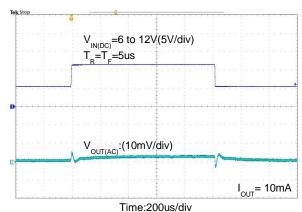


Line Transient Response V_{OUT}=5V

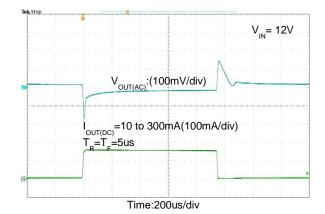


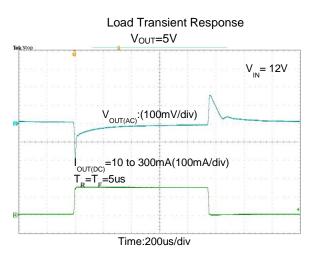
Typical Characteristics (continued)



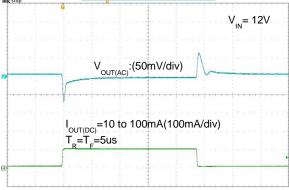


Load Transient Response $V_{OUT}=3.3V$

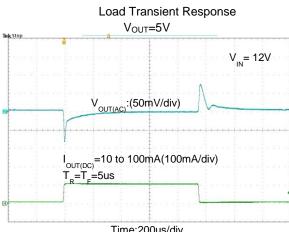




Load Transient Response V_{OUT}=3.3V



Time:200us/div



Time:200us/div



Application Information

Output Capacitor

An output capacitor is required for the stability of the LDO. The recommended minimum output capacitance is 1µF. A ceramic capacitor is recommended, and temperature characteristics are X7R or X5R. Higher capacitance values help to improve load/line transient response. The output capacitance may be increased to keep low undershoot/overshoot. Place the output capacitor as close as possible to VOUT and GND pins.

Input Capacitor

A 1µF ceramic capacitor is recommended to connect between VIN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both VIN and GND.

Current-Limit and Short-Circuit Protection

When output current at VOUT pin is higher than current-limit threshold or the VOUT pin directly shorts to GND, current-limit protection will trigger and clamp the output current at a pre-designed level to prevent overcurrent and thermal damage.

Thermal Protection

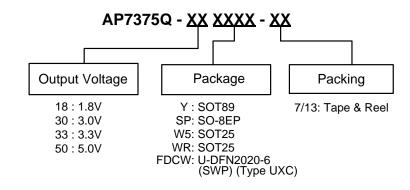
The AP7375Q has internal thermal sense and protection circuits. When excessive power dissipation happens on the device, such as short circuit at the output pin or very heavy load current with a large voltage drop across the device, the internal thermal protection circuit will trigger, shutting down the power MOSFET to prevent the LDO from damage. As soon as the excessive thermal condition is removed and the temperature of the device drops down, the thermal protection circuit will release the control of the power MOSFET, and the LDO device returns to normal operation.

Layout Considerations

For good ground loop and stability, the input and output capacitors should be located close to the input, output, and ground pins of the device. The regulator ground pin should be connected to the external circuit ground to reduce voltage drop caused by trace impedance. Ground plane is generally used to reduce trace impedance. Wide trace should be used for large current paths from V_{IN} to V_{OUT}, and load circuit.



Ordering Information



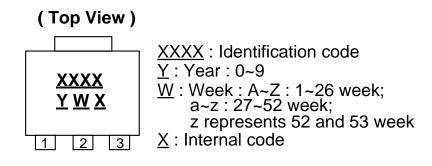
Orderable Part Number	Baakaga Cada	Package Code Package		e and Reel/Ammo	
Orderable Fart Nulliber	Fackage Code	Раскауе	Quantity	Part Number Suffix	
AP7375Q-XXY-13	Y	SOT89	2,500/Tape & Reel	-13	
AP7375Q-XXSP-13	SP	SO-8EP	2,500/Tape & Reel	-13	
AP7375Q-XXW5-7	W5	SOT25	3,000/Tape & Reel	-7	
AP7375Q-XXWR-7	WR	SOT25R	3,000/Tape & Reel	-7	
AP7375Q-XXFDCW-7 (*)	FDCW	U-DFN2020-6 (SWP) (Type UXC)	3,000/Tape & Reel	-7	

* Future Product



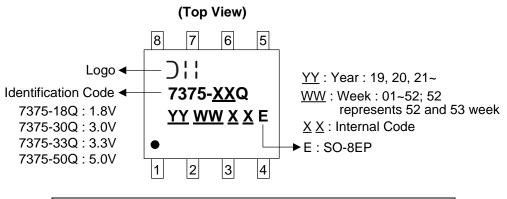
Marking Information

(1) SOT89



Orderable Part Number	Package	Identification Code
AP7375Q-18Y-13	SOT89	H5AQ
AP7375Q-30Y-13	SOT89	H5BQ
AP7375Q-33Y-13	SOT89	H5CQ
AP7375Q-50Y-13	SOT89	H5DQ

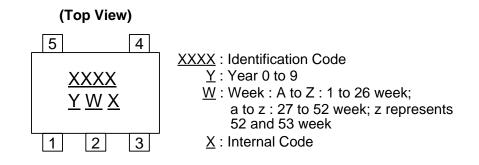
(2) SO-8EP



Orderable Part Number	Package	Identification Code
AP7375Q-18SP-13	SO-8EP	7375-18Q
AP7375Q-30SP-13	SO-8EP	7375-30Q
AP7375Q-33SP-13	SO-8EP	7375-33Q
AP7375Q-50SP-13	SO-8EP	7375-50Q

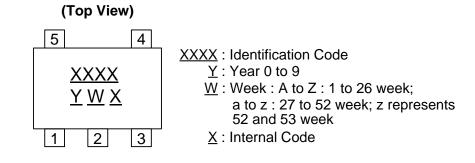


Marking Information (continued)



Orderable Part Number	Package	Identification Code
AP7375Q-18W5-7	SOT25	H5EQ
AP7375Q-30W5-7	SOT25	H5FQ
AP7375Q-33W5-7	SOT25	H5GQ
AP7375Q-50W5-7	SOT25	H5HQ

(4) SOT25R

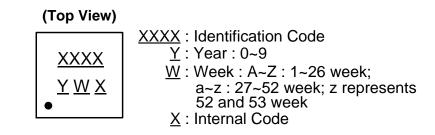


Orderable Part Number	Package	Identification Code
AP7375Q-18WR-7	SOT25R	H5AQ
AP7375Q-30WR-7	SOT25R	H5BQ
AP7375Q-33WR-7	SOT25R	H5CQ
AP7375Q-50WR-7	SOT25R	H5DQ



Marking Information (continued)

(5) U-DFN2020-6 (SWP) (Type UXC)

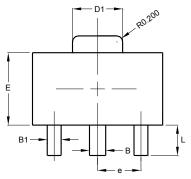


Orderable Part Number	Package	Identification Code
AP7375Q-18FDCW-7	U-DFN2020-6 (SWP) (Type UXC)	H5EQ
AP7375Q-30FDCW-7	U-DFN2020-6 (SWP) (Type UXC)	H5FQ
AP7375Q-33FDCW-7	U-DFN2020-6 (SWP) (Type UXC)	H5GQ
AP7375Q-50FDCW-7	U-DFN2020-6 (SWP) (Type UXC)	H5HQ



Package Outline Dimensions (All dimensions in mm.)

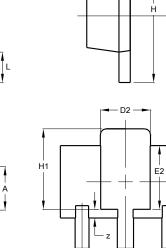
(1) SOT89



TOP VIEW

D

8° (84)



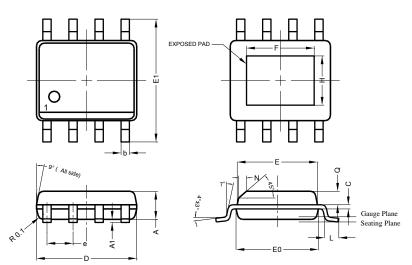
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L1

BOTTOM VIEW

	S	DT89	
Dim	Min	Max	Тур
Α	1.40	1.60	1.50
В	0.50	0.62	0.56
B1	0.42	0.54	0.48
С	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.62	1.83	1.733
D2	1.61	1.81	1.71
E	2.40	2.60	2.50
E2	2.05	2.35	2.20
е	-	-	1.50
н	3.95	4.25	4.10
H1	2.63	2.93	2.78
L	0.90	1.20	1.05
L1	0.327	0.527	0.427
z	0.20	0.40	0.30
All	Dimen	sions i	in mm

(2) Package Type: SO-8EP

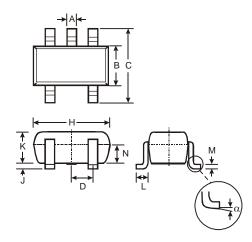


	SO-8	3EP	
Dim	Min	Max	Тур
Α	1.40	1.50	1.45
A1	0.00	0.13	1
b	0.30	0.50	0.40
С	0.15	0.25	0.20
D	4.85	4.95	4.90
E	3.80	3.90	3.85
E0	3.85	3.95	3.90
E1	5.90	6.10	6.00
е	-	-	1.27
F	2.75	3.35	3.05
Н	2.11	2.71	2.41
L	0.62	0.82	0.72
Ν	-	-	0.35
Q	0.60	0.70	0.65
All Di	mensi	ons in	mm



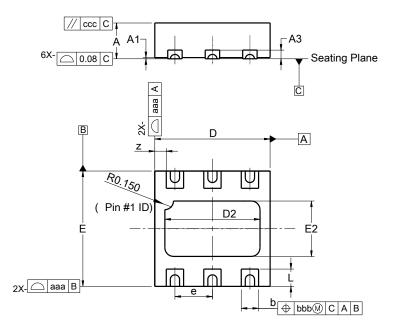
Package Outline Dimensions (All dimensions in mm.) (continued)

(3) Package Type: SOT25



SOT25				
Dim	Min	Max	Тур	
Α	0.35	0.50	0.38	
В	1.50	1.70	1.60	
С	2.70	3.00	2.80	
D	-	-	0.95	
н	2.90	3.10	3.00	
J	0.013	0.10	0.05	
κ	1.00	1.30	1.10	
L	0.35	0.55	0.40	
М	0.10	0.20	0.15	
Ν	0.70	0.80	0.75	
α	0°	8°	-	
All Dimensions in mm				

(4) U-DFN2020-6 (SWP) (Type UXC)

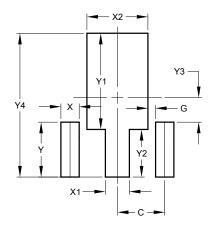


U	U-DFN2020-6 (SWP)				
	(Type UXC)				
Dim	Min	Max	Тур		
Α	0.57	0.63	0.60		
A1	0.00	0.05	0.02		
A3			0.13		
b	0.25	0.35	0.30		
D	1.95	2.075	2.00		
D2	1.55	1.75	1.65		
Е	1.95	2.075	2.00		
E2	0.86	1.06	0.96		
е			0.65		
L	0.25	0.35	0.30		
z			0.20		
aaa	0.25				
bbb	0.10				
CCC	0.10				
All Dimensions in mm					



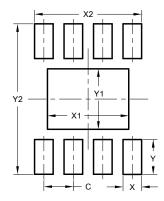
Suggested Pad Layout

(1) SOT89



Dimensions	Value (in mm)
С	1.500
G	0.244
Х	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

(2) Package Type: SO-8EP

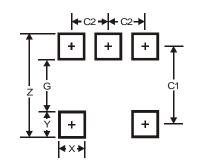


Dimensions	Value
Dimensions	(in mm)
С	1.270
Х	0.802
X1	3.502
X2	4.612
Y	1.505
Y1	2.613
Y2	6.500



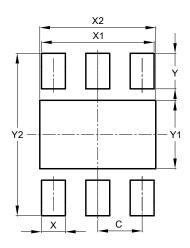
Suggested Pad Layout (continued)

(3) SOT25



Dimensions	Value (in mm)	
Z	3.20	
G	1.60	
Х	0.55	
Y	0.80	
C1	2.40	
C2	0.95	

(4) U-DFN2020-6 (SWP) (Type UXC)



Dimensions	Value (in mm)	
С	0.650	
Х	0.350	
X1	1.650	
X2	1.700	
Y	0.525	
Y1	1.010	
Y2	2.400	

Mechanical Data

- Moisture Sensitivity: Level 1 Per J-STD-020
- Terminals:
 - SOT89/ SO-8EP/ SOT25: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (3)
 - U-DFN2020-6 (SWP) (Type UXC): Finish –NiPdAu over Copper Leads, Solderable per MIL-STD-202, Method 208 4
- Weight:
 - SOT89: 0.054 grams (Approximate)
 - SO-8EP: 0.075 grams (Approximate)
 - SOT25: 0.018 grams (Approximate)
 - U-DFN2020-6 (SWP) (Type UXC): 0.007 grams (Approximate)



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